



Reflow Theoretical Profile

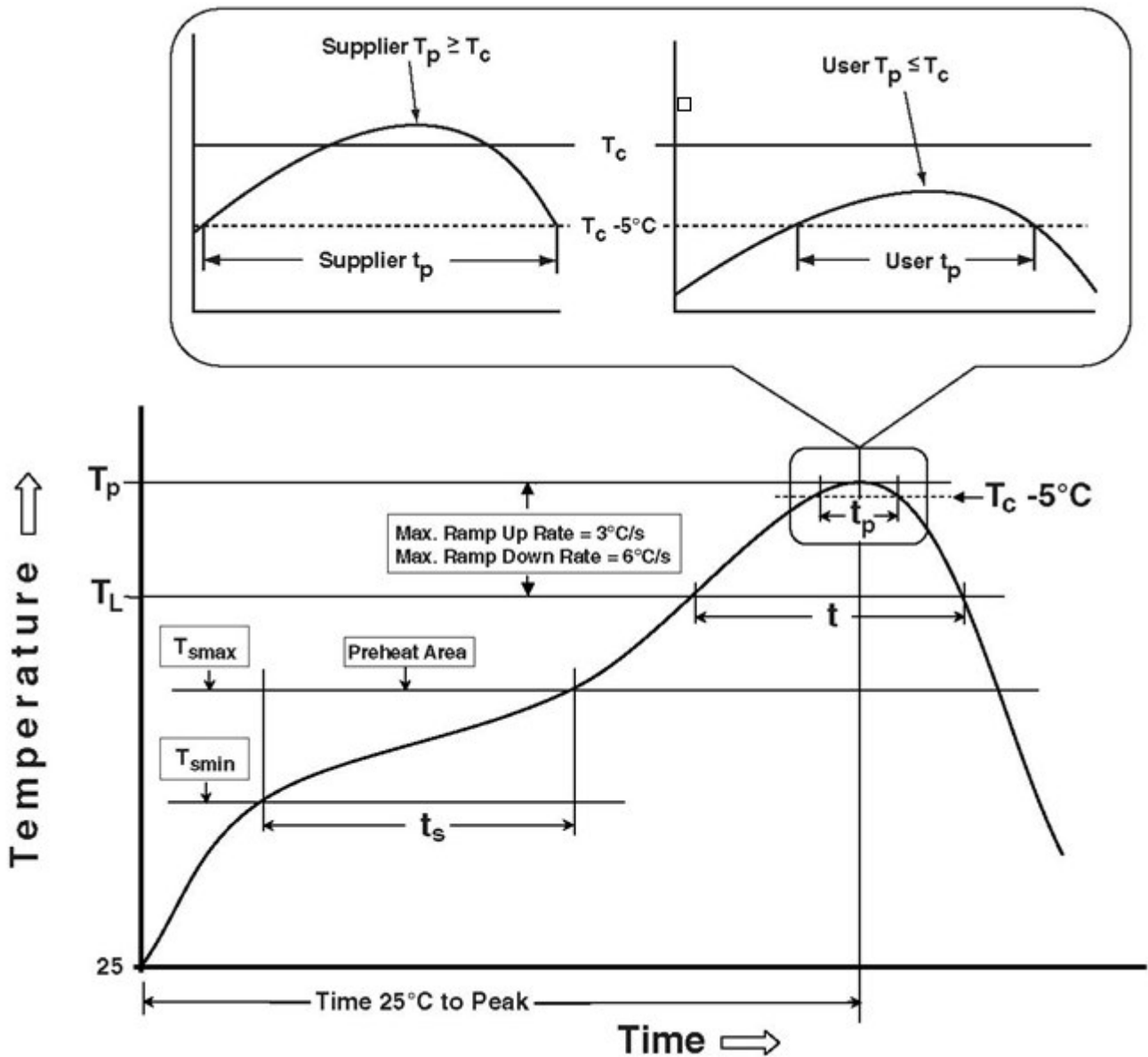




Table 1. Reflow Test Qualification

Profile Feature	Pb-Free Assembly
Preheat & Soak	
Temperature min (T _{min})	150 °C
Temperature max (T _{max})	200 °C
Time (T _{min} to T _{max}) (t _s)	60-120 seconds
Average ramp-up rate (T _{max} to T _p)	3 °C/second max.
Liquidous temperature (TL)	217 °C
Time at liquidous (t _L)	60-150 seconds
Peak package body temperature (T _p)*	See classification temp in Table 2
Time (t _p)** within 5 °C of the specified classification temperature (T _c)	30** seconds
Average ramp-down rate (T _p to T _{max})	6 °C/second max.
Time 25 °C to peak temperature	8 minutes max.
* Tolerance for peak profile temperature (T _p) is defined as a supplier minimum and a user maximum.	
** Tolerance for time at peak profile temperature (t _p) is defined as a supplier minimum and a user maximum.	

Table 2. Pb-Free Process - Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

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**Re-Flow Heat-Resisting
Temperature Conditions**
